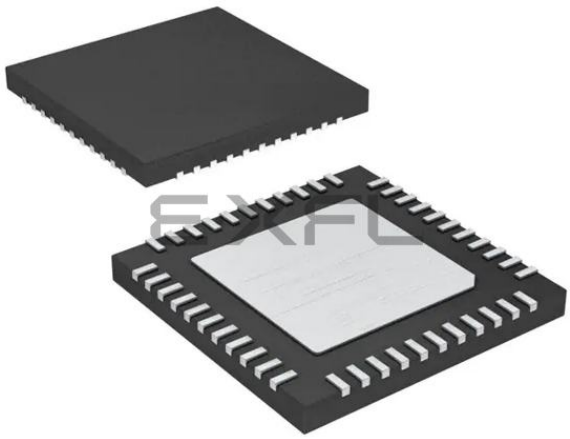

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Core Processor	PIC
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Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	35
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 30x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf44k22-e-ml

TABLE 1-3: PIC18(L)F4XK22 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Number				Pin Name	Pin Type	Buffer Type	Description
PDIP	TQFP	QFN	UQFN				
37	14	14	12	RB4/IOC0/T5G/AN11			
				RB4	I/O	TTL	Digital I/O.
				IOC0	I	TTL	Interrupt-on-change pin.
				T5G	I	ST	Timer5 external clock gate input.
				AN11	I	Analog	Analog input 11.
38	15	15	13	RB5/IOC1/P3A/CCP3/T3CKI/T1G/AN13			
				RB5	I/O	TTL	Digital I/O.
				IOC1	I	TTL	Interrupt-on-change pin.
				P3A(1)	O	CMOS	Enhanced CCP3 PWM output.
				CCP3(1)	I/O	ST	Capture 3 input/Compare 3 output/PWM 3 output.
				T3CKI(2)	I	ST	Timer3 clock input.
				T1G	I	ST	Timer1 external clock gate input.
				AN13	I	Analog	Analog input 13.
39	16	16	14	RB6/IOC2/PGC			
				RB6	I/O	TTL	Digital I/O.
				IOC2	I	TTL	Interrupt-on-change pin.
				PGC	I/O	ST	In-Circuit Debugger and ICSP™ programming clock pin.
40	17	17	15	RB7/IOC3/PGD			
				RB7	I/O	TTL	Digital I/O.
				IOC3	I	TTL	Interrupt-on-change pin.
				PGD	I/O	ST	In-Circuit Debugger and ICSP™ programming data pin.
15	32	34	30	RC0/P2B/T3CKI/T3G/T1CKI/SOSCO			
				RC0	I/O	ST	Digital I/O.
				P2B(2)	O	CMOS	Enhanced CCP1 PWM output.
				T3CKI(1)	I	ST	Timer3 clock input.
				T3G	I	ST	Timer3 external clock gate input.
				T1CKI	I	ST	Timer1 clock input.
				SOSCO	O	—	Secondary oscillator output.
16	35	35	31	RC1/P2A/CCP2/SOSCI			
				RC1	I/O	ST	Digital I/O.
				P2A(1)	O	CMOS	Enhanced CCP2 PWM output.
				CCP2(1)	I/O	ST	Capture 2 input/Compare 2 output/PWM 2 output.
				SOSCI	I	Analog	Secondary oscillator input.
17	36	36	32	RC2/CTPLS/P1A/CCP1/T5CKI/AN14			
				RC2	I/O	ST	Digital I/O.
				CTPLS	O	—	CTMU pulse generator output.
				P1A	O	CMOS	Enhanced CCP1 PWM output.
				CCP1	I/O	ST	Capture 1 input/Compare 1 output/PWM 1 output.
				T5CKI	I	ST	Timer5 clock input.
				AN14	I	Analog	Analog input 14.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power.

Note 1: Default pin assignment for P2B, T3CKI, CCP3/P3A and CCP2/P2A when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are set.

2: Alternate pin assignment for P2B, T3CKI, CCP3/P3A and CCP2/P2A when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are clear.

TABLE 5-2: REGISTER FILE SUMMARY FOR PIC18(L)F2X/4XK22 DEVICES (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR
F68h	CCPR2H	Capture/Compare/PWM Register 2, High Byte								xxxx xxxx
F67h	CCPR2L	Capture/Compare/PWM Register 2, Low Byte								xxxx xxxx
F66h	CCP2CON	P2M<1:0>		DC2B<1:0>		CCP2M<3:0>				0000 0000
F65h	PWM2CON	P2RSEN	P2DC<6:0>							0000 0000
F64h	ECCP2AS	CCP2ASE	CCP2AS<2:0>			PSS2AC<1:0>		PSS2BD<1:0>		0000 0000
F63h	PSTR2CON	—	—	—	STR2SYNC	STR2D	STR2C	STR2B	STR2A	---0 0001
F62h	IOCB	IOCB7	IOCB6	IOCB5	IOCB4	—	—	—	—	1111 ----
F61h	WPUB	WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0	1111 1111
F60h	SLRCON(2)	—	—	—	—	—	SLRC	SLRB	SLRA	---- -111
	SLRCON(1)	—	—	—	SLRE	SLRD	SLRC	SLRB	SLRA	---1 1111
F5Fh	CCPR3H	Capture/Compare/PWM Register 3, High Byte								xxxx xxxx
F5Eh	CCPR3L	Capture/Compare/PWM Register 3, Low Byte								xxxx xxxx
F5Dh	CCP3CON	P3M<1:0>		DC3B<1:0>		CCP3M<3:0>				0000 0000
F5Ch	PWM3CON	P3RSEN	P3DC<6:0>							0000 0000
F5Bh	ECCP3AS	CCP3ASE	CCP3AS<2:0>			PSS3AC<1:0>		PSS3BD<1:0>		0000 0000
F5Ah	PSTR3CON	—	—	—	STR3SYNC	STR3D	STR3C	STR3B	STR3A	---0 0001
F59h	CCPR4H	Capture/Compare/PWM Register 4, High Byte								xxxx xxxx
F58h	CCPR4L	Capture/Compare/PWM Register 4, Low Byte								xxxx xxxx
F57h	CCP4CON	—	—	DC4B<1:0>		CCP4M<3:0>				--00 0000
F56h	CCPR5H	Capture/Compare/PWM Register 5, High Byte								xxxx xxxx
F55h	CCPR5L	Capture/Compare/PWM Register 5, Low Byte								xxxx xxxx
F54h	CCP5CON	—	—	DC5B<1:0>		CCP5M<3:0>				--00 0000
F53h	TMR4	Timer4 Register								0000 0000
F52h	PR4	Timer4 Period Register								1111 1111
F51h	T4CON	—	T4OUTPS<3:0>				TMR4ON	T4CKPS<1:0>		-000 0000
F50h	TMR5H	Holding Register for the Most Significant Byte of the 16-bit TMR5 Register								0000 0000
F4Fh	TMR5L	Least Significant Byte of the 16-bit TMR5 Register								0000 0000
F4Eh	T5CON	TMR5CS<1:0>		T5CKPS<1:0>		T5SOSCEN	$\overline{\text{T5SYNC}}$	T5RD16	TMR5ON	0000 0000
F4Dh	T5GCON	TMR5GE	T5GPOL	T5GTM	T5GSPM	T5GGO/$\overline{\text{DONE}}$	T5GVAL	T5GSS<1:0>		0000 0x00
F4Ch	TMR6	Timer6 Register								0000 0000
F4Bh	PR6	Timer6 Period Register								1111 1111
F4Ah	T6CON	—	T6OUTPS<3:0>				TMR6ON	T6CKPS<1:0>		-000 0000
F49h	CCPTMRS0	C3TSEL<1:0>		—	C2TSEL<1:0>		—	C1TSEL<1:0>		00-0 0-00
F48h	CCPTMRS1	—	—	—	—	C5TSEL<1:0>		C4TSEL<1:0>		---- 0000
F47h	SRCON0	SRLEN	SRCLK<2:0>			SRQEN	SRNQEN	SRPS	SRPR	0000 0000
F46h	SRCON1	SRSPE	SRSCKE	SRSC2E	SRSC1E	SRRPE	SRRCKE	SRRC2E	SRRC1E	0000 0000
F45h	CTMUCONH	CTMUEN	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN	CTTRIG	0000 0000
F44h	CTMUCONL	EDG2POL	EDG2SEL<1:0>		EDG1POL	EDG1SEL<1:0>		EDG2STAT	EDG1STAT	0000 0000
F43h	CTMUICON	ITRIM<5:0>						IRNG<1:0>		0000 0000
F42h	VREFCON0	FVREN	FVRST	FVRS<1:0>		—	—	—	—	0001 ----
F41h	VREFCON1	DACEN	DACLPS	DACOE	—	DACPSS<1:0>		—	DACNSS	000- 00-0
F40h	VREFCON2	—	—	—	DACR<4:0>					---0 0000
F3Fh	PMD0	UART2MD	UART1MD	TMR6MD	TMR5MD	TMR4MD	TMR3MD	TMR2MD	TMR1MD	0000 0000
F3Eh	PMD1	MSSP2MD	MSSP1MD	—	CCP5MD	CCP4MD	CCP3MD	CCP2MD	CCP1MD	00-0 0000
F3Dh	PMD2	—	—	—	—	CTMUMD	CMP2MD	CMP1MD	ADCMD	---- 0000
F3Ch	ANSELE(1)	—	—	—	—	—	ANSE2	ANSE1	ANSE0	---- -111
F3Bh	ANSELD(1)	ANSD7	ANSD6	ANSD5	ANSD4	ANSD3	ANSD2	ANSD1	ANSD0	1111 1111

Legend: x = unknown, u = unchanged, — = unimplemented, q = value depends on condition

Note 1: PIC18(L)F4XK22 devices only.
2: PIC18(L)F2XK22 devices only.
3: PIC18(L)F23/24K22 and PIC18(L)F43/44K22 devices only.
4: PIC18(L)F26K22 and PIC18(L)F46K22 devices only.

EXAMPLE 6-3: WRITING TO FLASH PROGRAM MEMORY

```
                    MOVLW     D'64'                 ; number of bytes in erase block
                    MOVWF     COUNTER
                    MOVLW     BUFFER_ADDR_HIGH      ; point to buffer
                    MOVWF     FSR0H
                    MOVLW     BUFFER_ADDR_LOW
                    MOVWF     FSR0L
                    MOVLW     CODE_ADDR_UPPER       ; Load TBLPTR with the base
                    MOVWF     TBLPTRU               ; address of the memory block
                    MOVLW     CODE_ADDR_HIGH
                    MOVWF     TBLPTRH
                    MOVLW     CODE_ADDR_LOW
                    MOVWF     TBLPTRL
READ_BLOCK
                    TBLRD*+                         ; read into TABLAT, and inc
                    MOVF      TABLAT, W             ; get data
                    MOVWF     POSTINC0              ; store data
                    DECFSZ    COUNTER               ; done?
                    BRA       READ_BLOCK            ; repeat
MODIFY_WORD
                    MOVLW     BUFFER_ADDR_HIGH      ; point to buffer
                    MOVWF     FSR0H
                    MOVLW     BUFFER_ADDR_LOW
                    MOVWF     FSR0L
                    MOVLW     NEW_DATA_LOW          ; update buffer word
                    MOVWF     POSTINC0
                    MOVLW     NEW_DATA_HIGH
                    MOVWF     INDF0
ERASE_BLOCK
                    MOVLW     CODE_ADDR_UPPER       ; load TBLPTR with the base
                    MOVWF     TBLPTRU               ; address of the memory block
                    MOVLW     CODE_ADDR_HIGH
                    MOVWF     TBLPTRH
                    MOVLW     CODE_ADDR_LOW
                    MOVWF     TBLPTRL
                    BSF       EECON1, EEPGD         ; point to Flash program memory
                    BCF       EECON1, CFGS          ; access Flash program memory
                    BSF       EECON1, WREN          ; enable write to memory
                    BSF       EECON1, FREE          ; enable Erase operation
                    BCF       INTCON, GIE           ; disable interrupts
                    MOVLW     55h
Required            MOVWF     EECON2                ; write 55h
Sequence            MOVLW     0AAh
                    MOVWF     EECON2                ; write 0AAh
                    BSF       EECON1, WR            ; start erase (CPU stall)
                    BSF       INTCON, GIE           ; re-enable interrupts
                    TBLRD*-                         ; dummy read decrement
                    MOVLW     BUFFER_ADDR_HIGH      ; point to buffer
                    MOVWF     FSR0H
                    MOVLW     BUFFER_ADDR_LOW
                    MOVWF     FSR0L
WRITE_BUFFER_BACK
                    MOVLW     BlockSize             ; number of bytes in holding register
                    MOVWF     COUNTER
                    MOVLW     D'64'/BlockSize       ; number of write blocks in 64 bytes
                    MOVWF     COUNTER2
WRITE_BYTE_TO_HREGS
                    MOVF      POSTINC0, W           ; get low byte of buffer data
                    MOVWF     TABLAT                ; present data to table latch
                    TBLWT+*                         ; write data, perform a short write
                                                    ; to internal TBLWT holding register.
```

14.0 CAPTURE/COMPARE/PWM MODULES

The Capture/Compare/PWM module is a peripheral which allows the user to time and control different events, and to generate Pulse-Width Modulation (PWM) signals. In Capture mode, the peripheral allows the timing of the duration of an event. The Compare mode allows the user to trigger an external event when a predetermined amount of time has expired. The PWM mode can generate Pulse-Width Modulated signals of varying frequency and duty cycle.

This family of devices contains three Enhanced Capture/Compare/PWM modules (ECCP1, ECCP2, and ECCP3) and two standard Capture/Compare/PWM modules (CCP4 and CCP5).

The Capture and Compare functions are identical for all CCP/ECCP modules. The difference between CCP and ECCP modules are in the Pulse-Width Modulation (PWM) function. In CCP modules, the standard PWM function is identical. In ECCP modules, the Enhanced PWM function has either full-bridge or half-bridge PWM output. Full-bridge ECCP modules have four available I/O pins while half-bridge ECCP modules only have two available I/O pins. ECCP PWM modules are backward compatible with CCP PWM modules and can be configured as standard PWM modules. See Table 14-1 to determine the CCP/ECCP functionality available on each device in this family.

Note 1: In devices with more than one CCP module, it is very important to pay close attention to the register names used. A number placed after the module acronym is used to distinguish between separate modules. For example, the CCP1CON and CCP2CON control the same operational aspects of two completely different CCP modules.

2: Throughout this section, generic references to a CCP module in any of its operating modes may be interpreted as being equally applicable to ECCP1, ECCP2, ECCP3, CCP4 and CCP5. Register names, module signals, I/O pins, and bit names may use the generic designator ‘x’ to indicate the use of a numeral to distinguish a particular module, when required.

TABLE 14-1: PWM RESOURCES

Device Name	ECCP1	ECCP2	ECCP3	CCP4	CCP5
PIC18(L)F23K22 PIC18(L)F24K22 PIC18(L)F25K22 PIC18(L)F26K22	Enhanced PWM Full-Bridge	Enhanced PWM Half-Bridge	Enhanced PWM Half-Bridge	Standard PWM	Standard PWM (Special Event Trigger)
PIC18(L)F43K22 PIC18(L)F44K22 PIC18(L)F45K22 PIC18(L)F46K22	Enhanced PWM Full-Bridge	Enhanced PWM Full-Bridge	Enhanced PWM Half-Bridge	Standard PWM	Standard PWM (Special Event Trigger)

14.4.2.1 Direction Change in Full-Bridge Mode

In the Full-Bridge mode, the PxM1 bit in the CCPxCON register allows users to control the forward/reverse direction. When the application firmware changes this direction control bit, the module will change to the new direction on the next PWM cycle.

A direction change is initiated in software by changing the PxM1 bit of the CCPxCON register. The following sequence occurs four Timer cycles prior to the end of the current PWM period:

- The modulated outputs (PxB and PxD) are placed in their inactive state.
- The associated unmodulated outputs (PxA and PxC) are switched to drive in the opposite direction.
- PWM modulation resumes at the beginning of the next period.

See Figure 14-12 for an illustration of this sequence.

The Full-Bridge mode does not provide dead-band delay. As one output is modulated at a time, dead-band delay is generally not required. There is a situation where dead-band delay is required.

This situation occurs when both of the following conditions are true:

1. The direction of the PWM output changes when the duty cycle of the output is at or near 100%.
2. The turn off time of the power switch, including the power device and driver circuit, is greater than the turn on time.

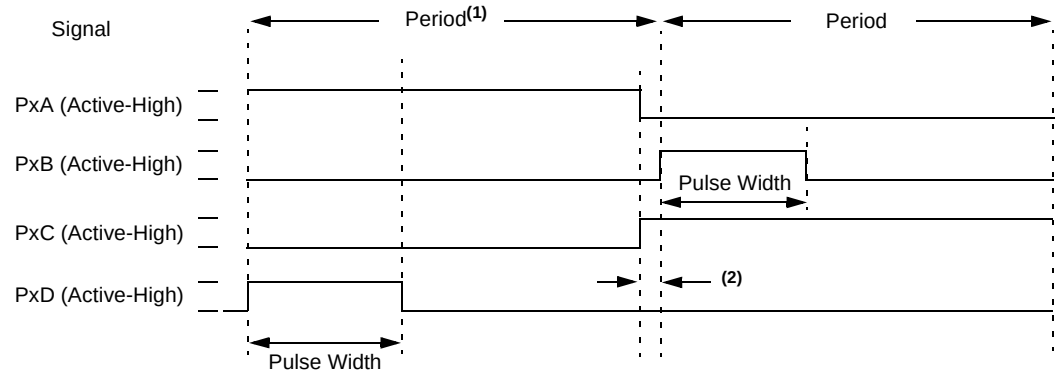
Figure 14-13 shows an example of the PWM direction changing from forward to reverse, at a near 100% duty cycle. In this example, at time t1, the output PxA and PxD become inactive, while output PxC becomes active. Since the turn off time of the power devices is longer than the turn on time, a shoot-through current will flow through power devices QC and QD (see Figure 14-10) for the duration of ‘t’. The same phenomenon will occur to power devices QA and QB for PWM direction change from reverse to forward.

If changing PWM direction at high duty cycle is required for an application, two possible solutions for eliminating the shoot-through current are:

1. Reduce PWM duty cycle for one PWM period before changing directions.
2. Use switch drivers that can drive the switches off faster than they can drive them on.

Other options to prevent shoot-through current may exist.

FIGURE 14-12: EXAMPLE OF PWM DIRECTION CHANGE



Note 1: The direction bit PxM1 of the CCPxCON register is written any time during the PWM cycle.

2: When changing directions, the PxA and PxC signals switch before the end of the current PWM cycle. The modulated PxB and PxD signals are inactive at this time. The length of this time is (TimerX Prescale)/FOSC, where TimerX is Timer2, Timer4 or Timer6.

REGISTER 14-5: ECCPxAS: CCPX AUTO-SHUTDOWN CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CCPxASE	CCPxAS<2:0>			PSSxAC<1:0>		PSSxBD<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **CCPxASE:** CCPx Auto-shutdown Event Status bit
if PxRSEN = 1;
1 = An Auto-shutdown event occurred; CCPxASE bit will automatically clear when event goes away; CCPx outputs in shutdown state
0 = CCPx outputs are operating
if PxRSEN = 0;
1 = An Auto-shutdown event occurred; bit must be cleared in software to restart PWM; CCPx outputs in shutdown state
0 = CCPx outputs are operating

bit 6-4 **CCPxAS<2:0>:** CCPx Auto-Shutdown Source Select bits **(1)**
000 = Auto-shutdown is disabled
001 = Comparator C1 (async_C1OUT) – output high will cause shutdown event
010 = Comparator C2 (async_C2OUT) – output high will cause shutdown event
011 = Either Comparator C1 or C2 – output high will cause shutdown event
100 = FLT0 pin – low level will cause shutdown event
101 = FLT0 pin – low level or Comparator C1 (async_C1OUT) – high level will cause shutdown event
110 = FLT0 pin – low level or Comparator C2 (async_C2OUT) – high level will cause shutdown event
111 = FLT0 pin – low level or Comparators C1 or C2 – high level will cause shutdown event

bit 3-2 **PSSxAC<1:0>:** Pins PxA and PxC Shutdown State Control bits
00 = Drive pins PxA and PxC to '0'
01 = Drive pins PxA and PxC to '1'
1x = Pins PxA and PxC tri-state

bit 1-0 **PSSxBD<1:0>:** Pins PxB and PxD Shutdown State Control bits
00 = Drive pins PxB and PxD to '0'
01 = Drive pins PxB and PxD to '1'
1x = Pins PxB and PxD tri-state

Note 1: If C1SYNC or C2SYNC bits in the CM2CON1 register are enabled, the shutdown will be delayed by Timer1.

FIGURE 15-7: SPI DAISY-CHAIN CONNECTION

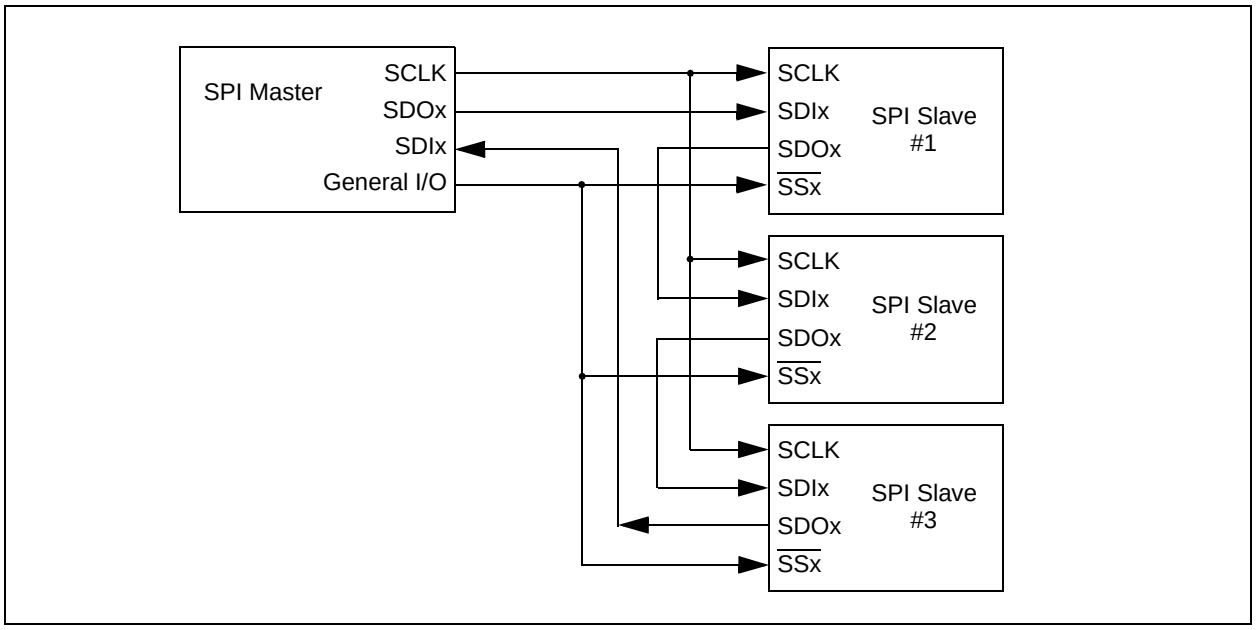
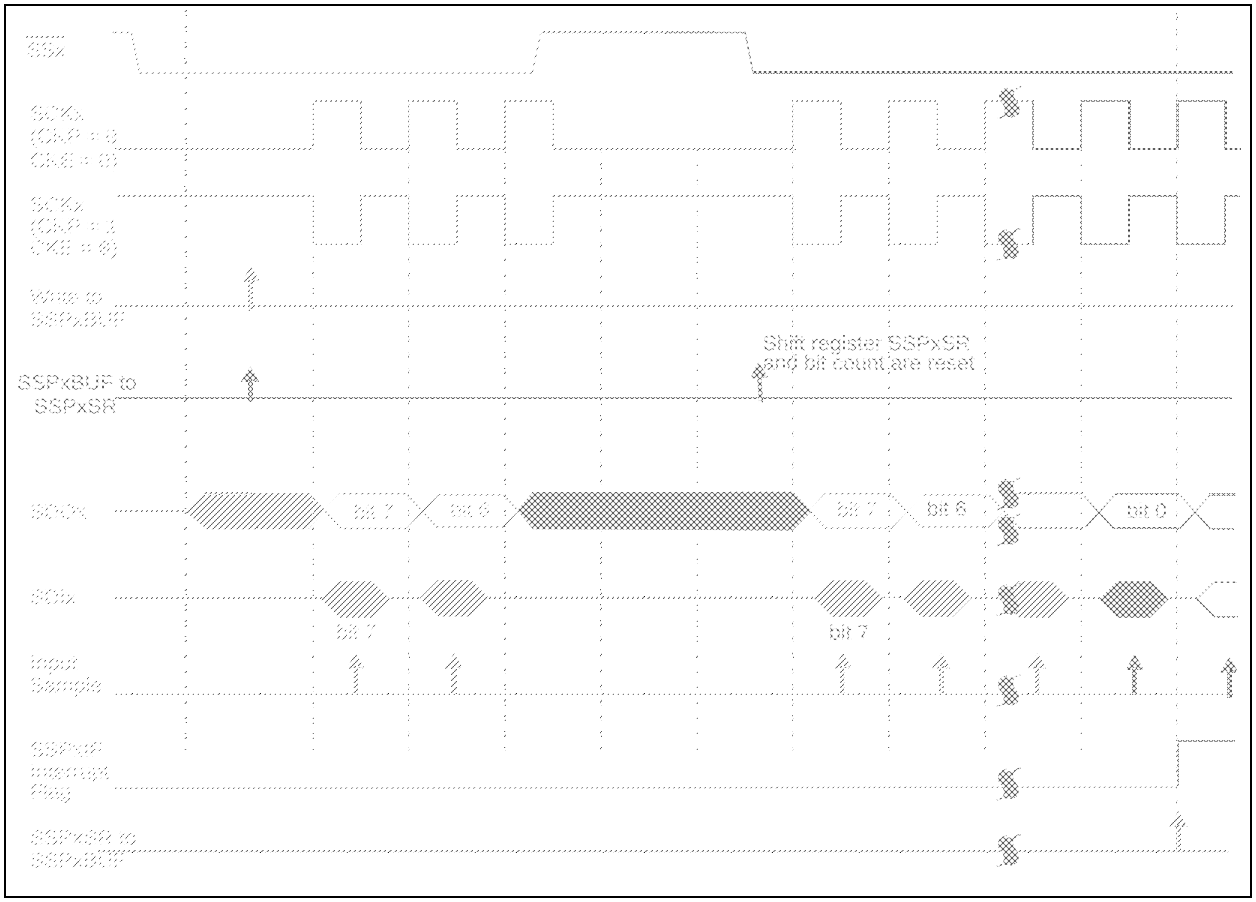


FIGURE 15-8: SLAVE SELECT SYNCHRONOUS WAVEFORM



15.5.4 SLAVE MODE 10-BIT ADDRESS RECEPTION

This section describes a standard sequence of events for the MSSPx module configured as an I^2C slave in 10-bit Addressing mode (Figure 15-20) and is used as a visual reference for this description.

This is a step by step process of what must be done by slave software to accomplish I^2C communication.

1. Bus starts Idle.
2. Master sends Start condition; S bit of SSPxSTAT is set; SSPxIF is set if interrupt on Start detect is enabled.
3. Master sends matching high address with R/$\overline{W}$ bit clear; UA bit of the SSPxSTAT register is set.
4. Slave sends $\overline{ACK}$ and SSPxIF is set.
5. Software clears the SSPxIF bit.
6. Software reads received address from SSPxBUF clearing the BF flag.
7. Slave loads low address into SSPxADD, releasing SCLx.
8. Master sends matching low address byte to the slave; UA bit is set.

Note:	Updates to the SSPxADD register are not allowed until after the $\overline{ACK}$ sequence.

9. Slave sends $\overline{ACK}$ and SSPxIF is set.

Note:	If the low address does not match, SSPxIF and UA are still set so that the slave software can set SSPxADD back to the high address. BF is not set because there is no match. CKP is unaffected.

10. Slave clears SSPxIF.
11. Slave reads the received matching address from SSPxBUF clearing BF.
12. Slave loads high address into SSPxADD.
13. Master clocks a data byte to the slave and clocks out the slaves $\overline{ACK}$ on the 9th SCLx pulse; SSPxIF is set.
14. If SEN bit of SSPxCON2 is set, CKP is cleared by hardware and the clock is stretched.
15. Slave clears SSPxIF.
16. Slave reads the received byte from SSPxBUF clearing BF.
17. If SEN is set the slave sets CKP to release the SCLx.
18. Steps 13-17 repeat for each received byte.
19. Master sends Stop to end the transmission.

15.5.5 10-BIT ADDRESSING WITH ADDRESS OR DATA HOLD

Reception using 10-bit addressing with AHEN or DHEN set is the same as with 7-bit modes. The only difference is the need to update the SSPxADD register using the UA bit. All functionality, specifically when the CKP bit is cleared and SCLx line is held low are the same. Figure 15-21 can be used as a reference of a slave in 10-bit addressing with AHEN set.

Figure 15-22 shows a standard waveform for a slave transmitter in 10-bit Addressing mode.

19.6 Creating a Delay with the CTMU Module

A unique feature on board the CTMU module is its ability to generate system clock independent output pulses based on an external capacitor value. This is accomplished using the internal comparator voltage reference module, Comparator 2 input pin and an external capacitor. The pulse is output onto the CTPLS pin. To enable this mode, set the TGEN bit.

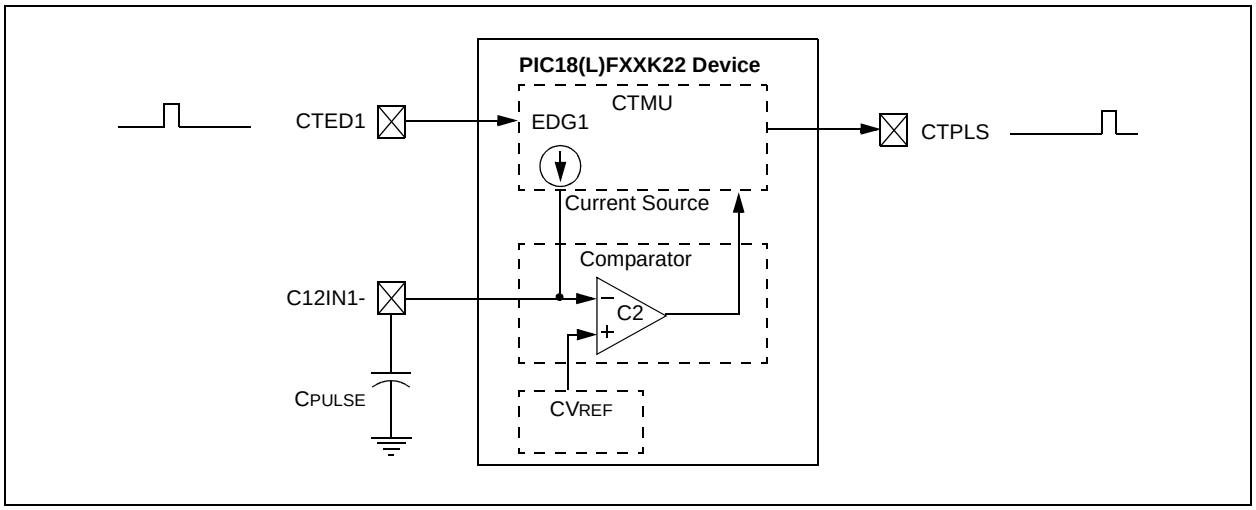
See Figure 19-4 for an example circuit. C_{PULSE} is chosen by the user to determine the output pulse width on CTPLS. The pulse width is calculated by $T = (C_{PULSE}/I) * V$, where I is known from the current source measurement step (**Section 19.3.1 "Current Source Calibration"**) and V is the internal reference voltage (CV_{REF}).

An example use of this feature is for interfacing with variable capacitive-based sensors, such as a humidity sensor. As the humidity varies, the pulse width output on CTPLS will vary. The CTPLS output pin can be connected to an input capture pin and the varying pulse width is measured to determine the humidity in the application.

Follow these steps to use this feature:

1. Initialize Comparator 2.
2. Initialize the comparator voltage reference.
3. Initialize the CTMU and enable time delay generation by setting the TGEN bit.
4. Set EDG1STAT.
5. When C_{PULSE} charges to the value of the voltage reference trip point, an output pulse is generated on CTPLS.

FIGURE 19-4: TYPICAL CONNECTIONS AND INTERNAL CONFIGURATION FOR PULSE DELAY GENERATION



19.7 Operation During Sleep/Idle Modes

19.7.1 SLEEP MODE AND DEEP SLEEP MODES

When the device enters any Sleep mode, the CTMU module current source is always disabled. If the CTMU is performing an operation that depends on the current source when Sleep mode is invoked, the operation may not terminate correctly. Capacitance and time measurements may return erroneous values.

19.7.2 IDLE MODE

The behavior of the CTMU in Idle mode is determined by the CTMUSIDL bit (CTMUCONH<5>). If CTMUSIDL is cleared, the module will continue to operate in Idle mode. If CTMUSIDL is set, the module's current source is disabled when the device enters Idle mode. If the module is performing an operation when Idle mode is invoked, in this case, the results will be similar to those with Sleep mode.

19.8 CTMU Peripheral Module Disable (PMD)

When this peripheral is not used, the Peripheral Module Disable bit can be set to disconnect all clock sources to the module, reducing power consumption to an absolute minimum. See **Section 3.6 "Selective Peripheral Module Control"**.

FIGURE 20-1: DIVSRCLK BLOCK DIAGRAM

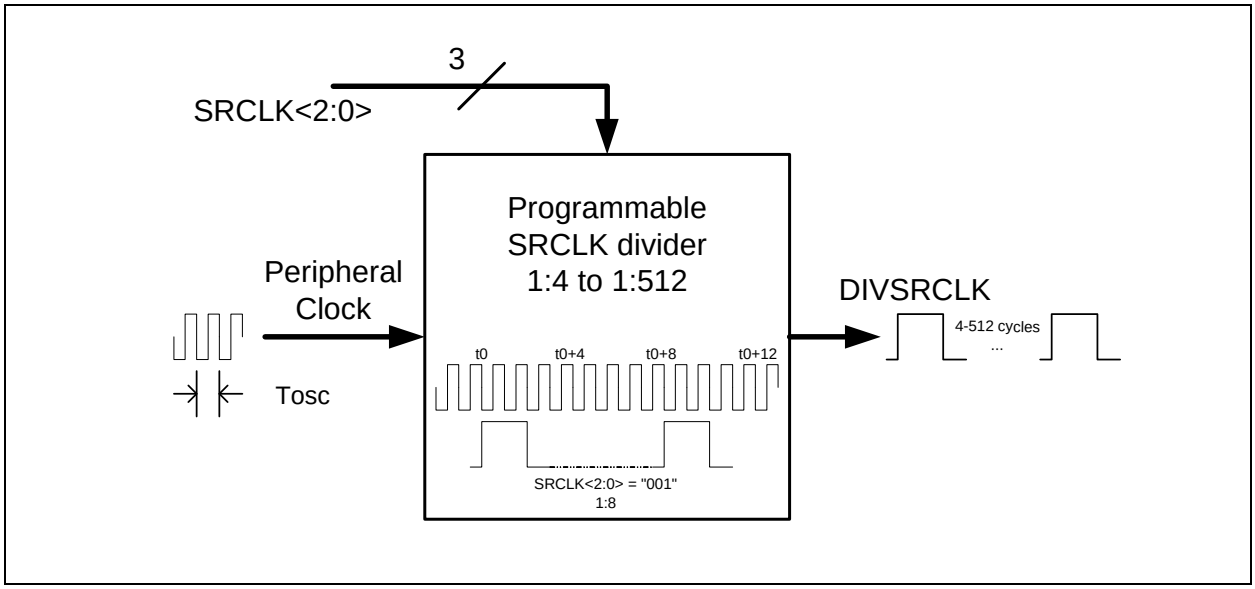
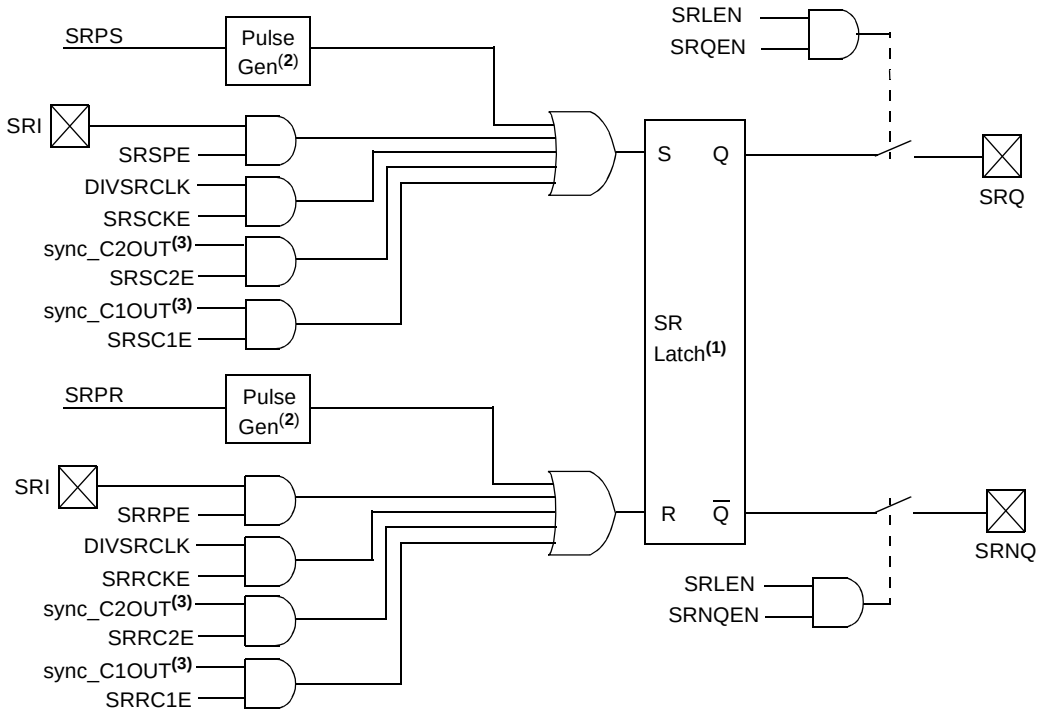


FIGURE 20-2: SR LATCH SIMPLIFIED BLOCK DIAGRAM



Note 1: If R = 1 and S = 1 simultaneously, Q = 0, $\overline{Q}$ = 1
2: Pulse generator causes a pulse width of 2 TOSC clock cycles.
3: Name denotes the connection point at the comparator output.

21.0 FIXED VOLTAGE REFERENCE (FVR)

The Fixed Voltage Reference, or FVR, is a stable voltage reference, independent of VDD, with 1.024V, 2.048V or 4.096V selectable output levels. The output of the FVR can be configured to supply a reference voltage to the following:

- ADC input channel
- ADC positive reference
- Comparator positive input
- Digital-to-Analog Converter (DAC)

The FVR can be enabled by setting the FVREN bit of the VREFCON0 register.

21.1 Independent Gain Amplifiers

The output of the FVR supplied to the ADC, Comparators and DAC is routed through an independent programmable gain amplifier. The amplifier can be configured to amplify the 1.024V reference voltage by 1x, 2x or 4x, to produce the three possible voltage levels.

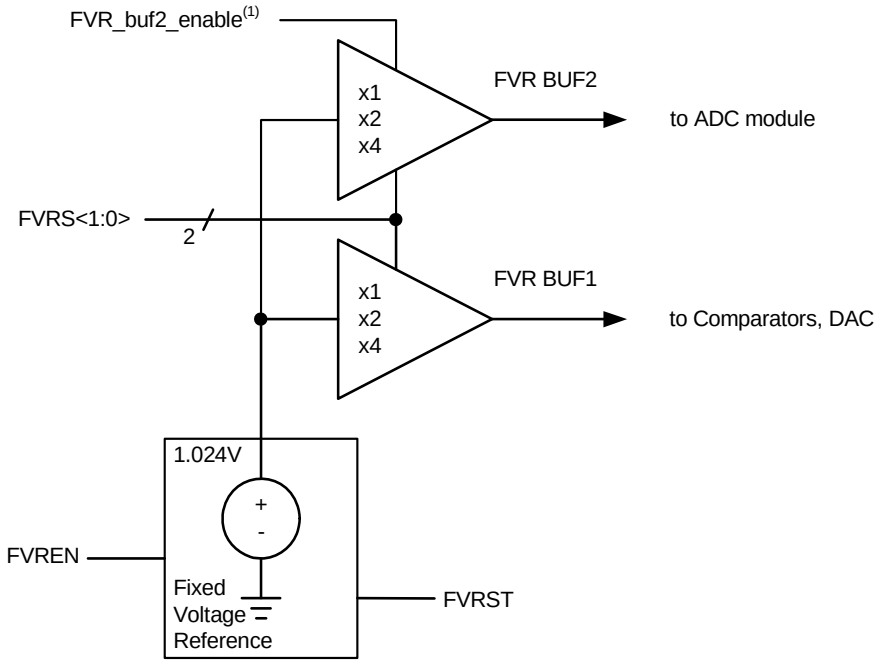
The FVRS<1:0> bits of the VREFCON0 register are used to enable and configure the gain amplifier settings for the reference supplied to the DAC and Comparator modules. When the ADC module is configured to use the FVR output, (FVR BUF2) the reference is buffered through an additional unity gain amplifier. This buffer is disabled if the ADC is not configured to use the FVR.

For specific use of the FVR, refer to the specific module sections: **Section 17.0 “Analog-to-Digital Converter (ADC) Module”**, **Section 22.0 “Digital-to-Analog Converter (DAC) Module”** and **Section 18.0 “Comparator Module”**.

21.2 FVR Stabilization Period

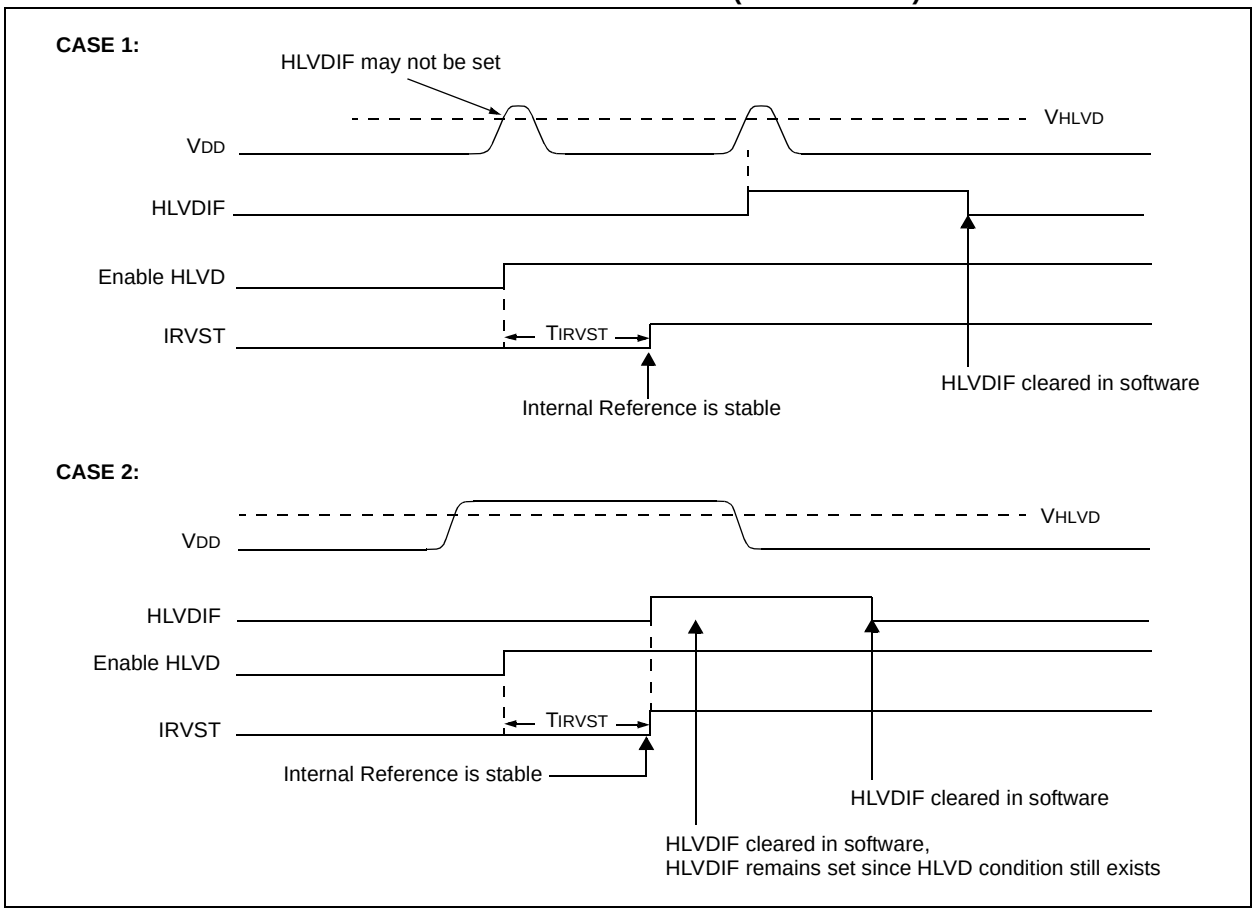
When the Fixed Voltage Reference module is enabled, it requires time for the reference and amplifier circuits to stabilize. Once the circuits stabilize and are ready for use, the FVRST bit of the VREFCON0 register will be set. See Table 27-3 for the minimum delay requirement.

FIGURE 21-1: VOLTAGE REFERENCE BLOCK DIAGRAM



Note 1: FVR_buf2_enable = ‘1’ when (ADON = ‘1’) AND [(PVCFG<1:0> = ‘10’) OR (CHS<4:0> = ‘11111’)]

FIGURE 23-3: HIGH-VOLTAGE DETECT OPERATION (VDIRMAG = 1)



23.6 Applications

In many applications, it is desirable to detect a drop below, or rise above, a particular voltage threshold. For example, the HLVD module could be periodically enabled to detect Universal Serial Bus (USB) attach or detach. This assumes the device is powered by a lower voltage source than the USB when detached. An attach would indicate a high-voltage detect from, for example, 3.3V to 5V (the voltage on USB) and vice versa for a detach. This feature could save a design a few extra components and an attach signal (input pin).

For general battery applications, Figure 23-4 shows a possible voltage curve. Over time, the device voltage decreases. When the device voltage reaches voltage VA, the HLVD logic generates an interrupt at time, TA. The interrupt could cause the execution of an ISR, which would allow the application to perform "house-keeping tasks" and a controlled shutdown before the device voltage exits the valid operating range at TB. This would give the application a time window, represented by the difference between TA and TB, to safely exit.

FIGURE 23-4: TYPICAL LOW-VOLTAGE DETECT APPLICATION

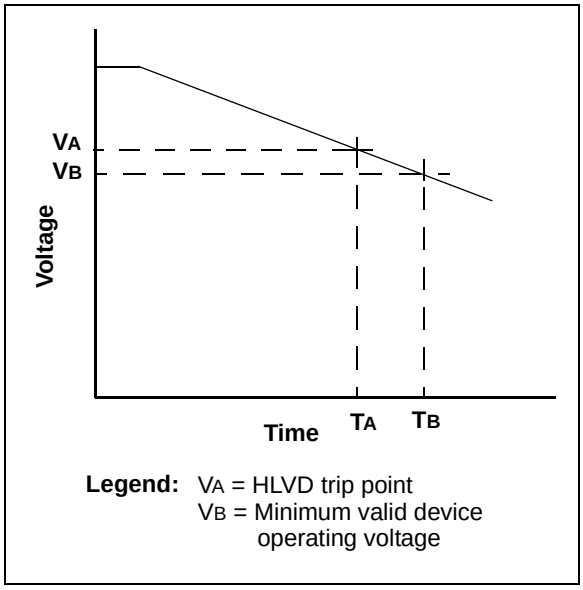


TABLE 24-2: DEVICE ID TABLE FOR THE PIC18(L)F2X/4XK22 FAMILY

DEV<10:3>	DEV<2:0>	Part Number
0101 0100	000	PIC18F46K22
	001	PIC18LF46K22
	010	PIC18F26K22
	011	PIC18LF26K22
0101 0101	000	PIC18F45K22
	001	PIC18LF45K22
	010	PIC18F25K22
	011	PIC18LF25K22
0101 0110	000	PIC18F44K22
	001	PIC18LF44K22
	010	PIC18F24K22
	011	PIC18LF24K22
0101 0111	000	PIC18F43K22
	001	PIC18LF43K22
	010	PIC18F23K22
	011	PIC18LF23K22

TABLE 25-2: PIC18(L)F2X/4XK22 INSTRUCTION SET (CONTINUED)

Mnemonic, Operands		Description	Cycles	16-Bit Instruction Word				Status Affected	Notes
				MSb			LSb		
LITERAL OPERATIONS									
ADDLW	k	Add literal and WREG	1	0000	1111	kkkk	kkkk	C, DC, Z, OV, N	
ANDLW	k	AND literal with WREG	1	0000	1011	kkkk	kkkk	Z, N	
IORLW	k	Inclusive OR literal with WREG	1	0000	1001	kkkk	kkkk	Z, N	
LFSR	f, k	Move literal (12-bit) 2nd word	2	1110	1110	00ff	kkkk	None	
		to FSR(f) 1st word		1111	0000	kkkk	kkkk		
MOVLB	k	Move literal to BSR<3:0>	1	0000	0001	0000	kkkk	None	
MOVLW	k	Move literal to WREG	1	0000	1110	kkkk	kkkk	None	
MULLW	k	Multiply literal with WREG	1	0000	1101	kkkk	kkkk	None	
RETLW	k	Return with literal in WREG	2	0000	1100	kkkk	kkkk	None	
SUBLW	k	Subtract WREG from literal	1	0000	1000	kkkk	kkkk	C, DC, Z, OV, N	
XORLW	k	Exclusive OR literal with WREG	1	0000	1010	kkkk	kkkk	Z, N	
DATA MEMORY ↔ PROGRAM MEMORY OPERATIONS									
TBLRD*		Table Read	2	0000	0000	0000	1000	None	
TBLRD*+		Table Read with post-increment		0000	0000	0000	1001	None	
TBLRD*-		Table Read with post-decrement		0000	0000	0000	1010	None	
TBLRD+*		Table Read with pre-increment		0000	0000	0000	1011	None	
TBLWT*		Table Write	2	0000	0000	0000	1100	None	
TBLWT*+		Table Write with post-increment		0000	0000	0000	1101	None	
TBLWT*-		Table Write with post-decrement		0000	0000	0000	1110	None	
TBLWT+*		Table Write with pre-increment		0000	0000	0000	1111	None	

Note 1: When a PORT register is modified as a function of itself (e.g., `MOVF PORTB, 1, 0`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and where applicable, 'd' = 1), the prescaler will be cleared if assigned.

3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

4: Some instructions are two-word instructions. The second word of these instructions will be executed as a NOP unless the first word of the instruction retrieves the information embedded in these 16 bits. This ensures that all program memory locations have a valid instruction.

RLNCF **Rotate Left f (No Carry)**

Syntax: RLNCF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

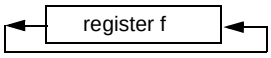
Operation: (f<n>) → dest<n + 1>,
(f<7>) → dest<0>

Status Affected: N, Z

Encoding:

0100	01da	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the left. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register 'f' (default).
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: RLNCF REG, 1, 0

Before Instruction
REG = 1010 1011
After Instruction
REG = 0101 0111

RRCF **Rotate Right f through Carry**

Syntax: RRCF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

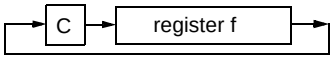
Operation: (f<n>) → dest<n – 1>,
(f<0>) → C,
(C) → dest<7>

Status Affected: C, N, Z

Encoding:

0011	00da	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the right through the CARRY flag. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f' (default).
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever f ≤ 95 (5Fh). See **Section 25.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.



Words: 1

Cycles: 1

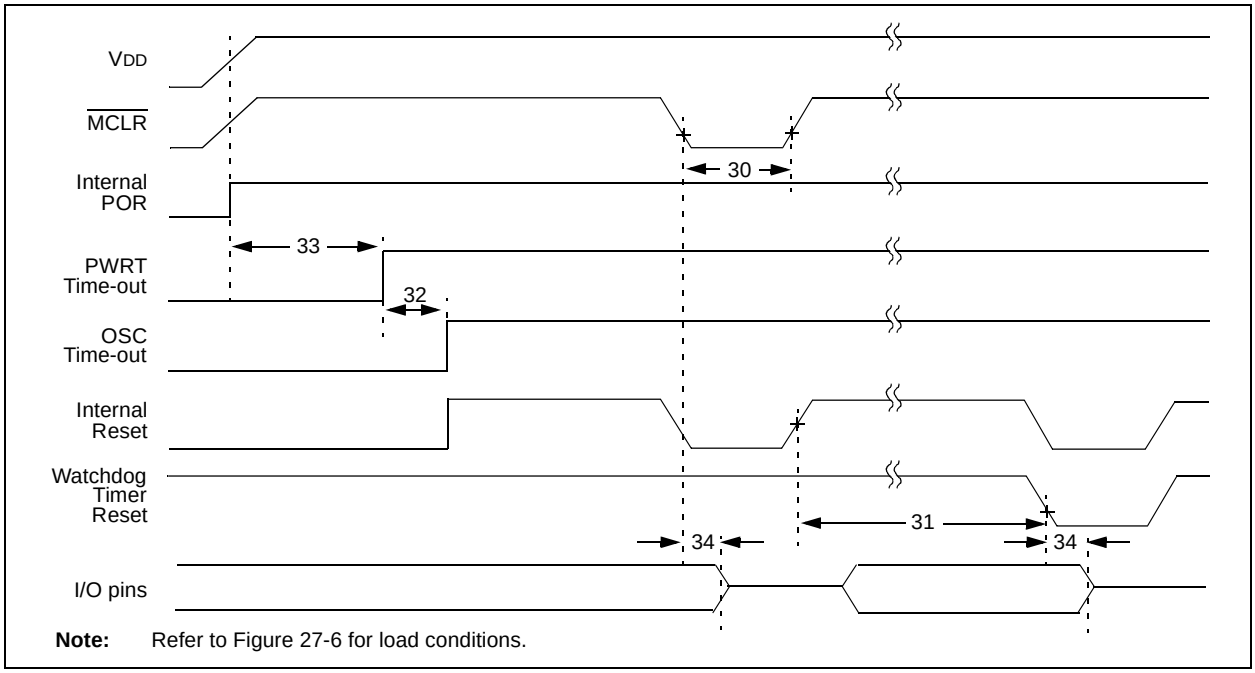
Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: RRCF REG, 0, 0

Before Instruction
REG = 1110 0110
C = 0
After Instruction
REG = 1110 0110
W = 0111 0011
C = 0

FIGURE 27-9: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note: Refer to Figure 27-6 for load conditions.

FIGURE 27-10: BROWN-OUT RESET TIMING

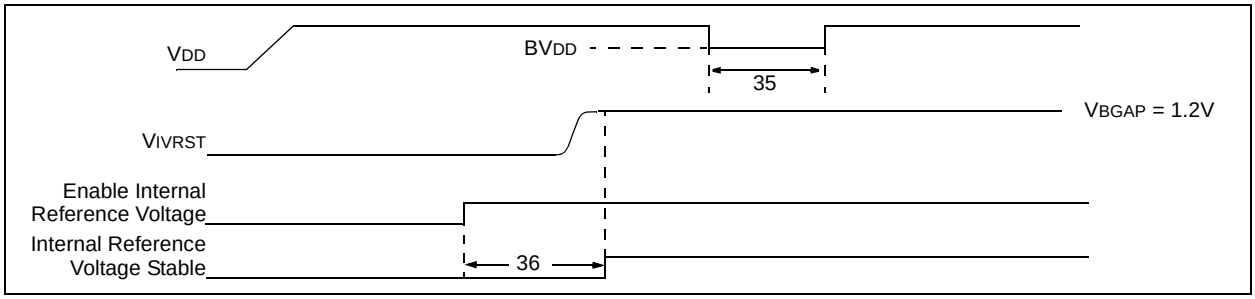
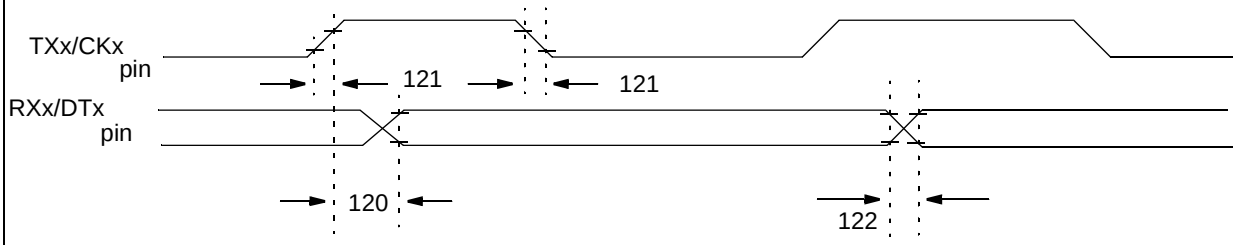


FIGURE 27-21: EUSART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

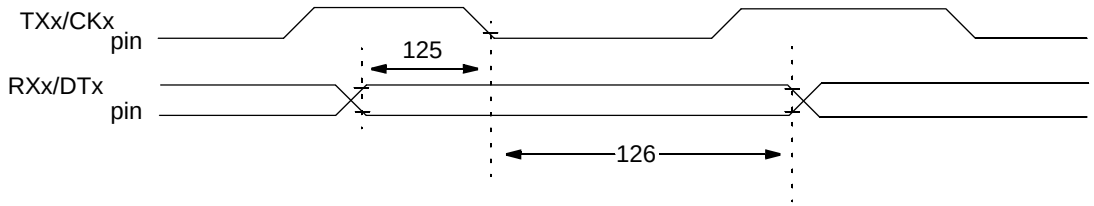


Note: Refer to Figure 27-6 for load conditions.

TABLE 27-19: EUSART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Param. No.	Symbol	Characteristic	Min	Max	Units	Conditions
120	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock High to Data Out Valid	—	40	ns	
121	Tckrf	Clock Out Rise Time and Fall Time (Master mode)	—	20	ns	
122	Tdtrf	Data Out Rise Time and Fall Time	—	20	ns	

FIGURE 27-22: EUSART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



Note: Refer to Figure 27-6 for load conditions.

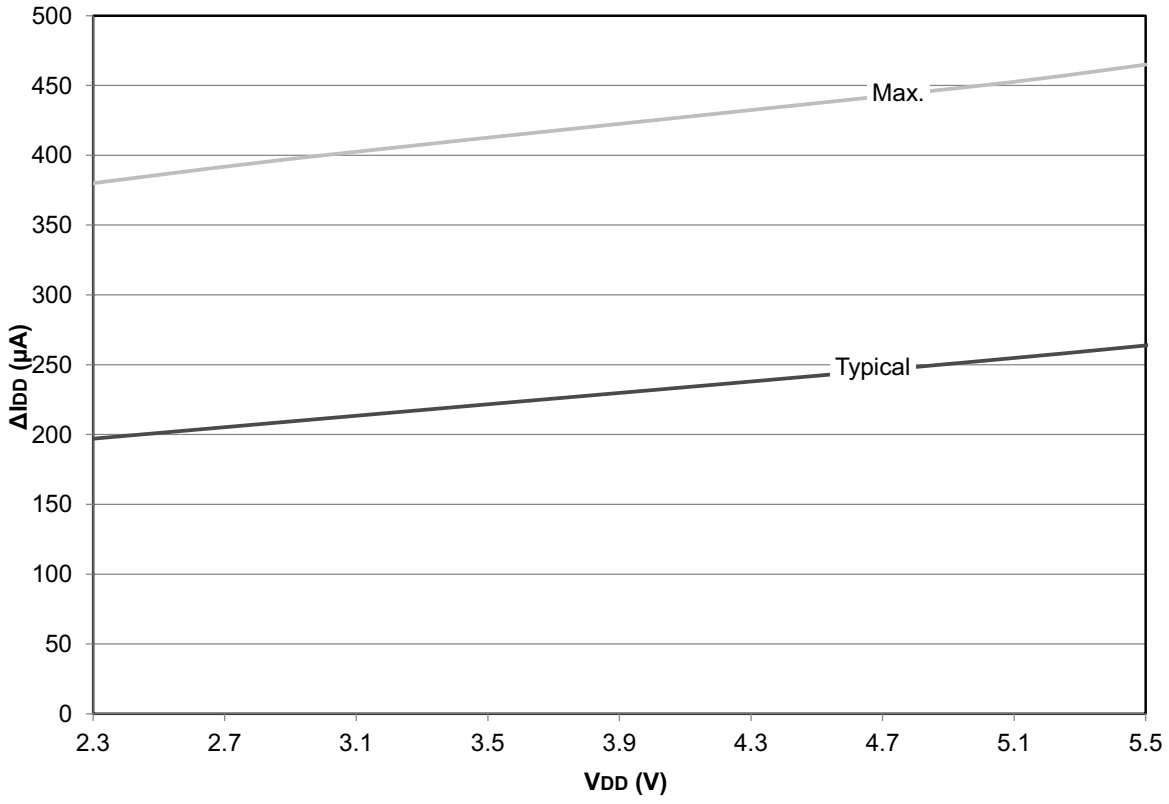
TABLE 27-20: EUSART SYNCHRONOUS RECEIVE REQUIREMENTS

Param. No.	Symbol	Characteristic	Min	Max	Units	Conditions
125	TdtV2ckl	SYNC RCV (MASTER & SLAVE) Data Setup before CK ↓ (DT setup time)	10	—	ns	
126	TckL2dtl	Data Hold after CK ↓ (DT hold time)	15	—	ns	

28.0 DC AND AC CHARACTERISTICS GRAPHS AND CHARTS

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g. outside specified power supply range) and therefore, outside the warranted range.

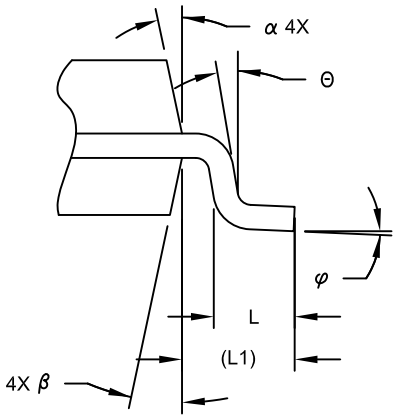
FIGURE 28-19: PIC18(L)F2X/4XK22 DELTA IDD A/D CONVERTOR[1]



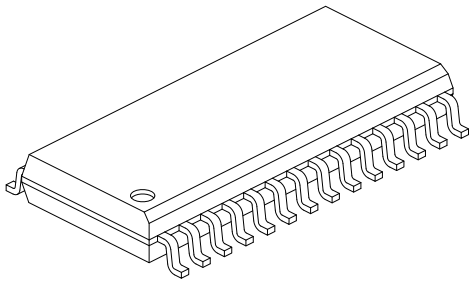
Note 1: A/D converter differential currents apply only in Run mode. In Sleep or Idle mode, both the ADC and the FRC turn off as soon as conversion (if any) is complete.

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2